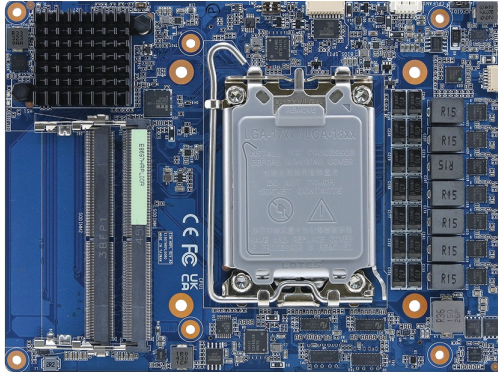




ESM-HRPL

COM-HPC® Client Size C Module. LGA17xx/LGA18xx socket supports 12/13/14th Gen Intel® Core™ Processors



Features

- LGA17xx/LGA18xx socket supports 12/13/14th Gen Intel® Core™ i9/i7/i5/i3 Processor, up to 65W TDP
- Intel® R680E Chipset
- 4 x 262-Pin DDR5 SO-DIMM sockets support up to 128GB, 3600~4000MT/s, optional ECC support (CPU dependent)
- Supports 4 Independent Display
- Supports 1 x PCIe Gen5 x16 , 1 x PEG x4, 2 x PCIe x4, 9 x PCIe Gen3 x1, 1 x PCIe Gen3 x1 for BMC
- 2 x Intel® Ethernet Controller I226-V (2.5GbE)
- Supports 3 x DDI, 1 x eDP
- Supports 4 x USB3.2 Gen2x2, 8 x USB2.0, 2x SATAIII
- Supports 1 x Audio, 1 x I2C, 1 x SMBus, 1 x GSPI, 1 x IPMB, 1 x SPI
- Supports Standard Operating Temperature 0°C ~ 60°C (32°F ~ 140°F)

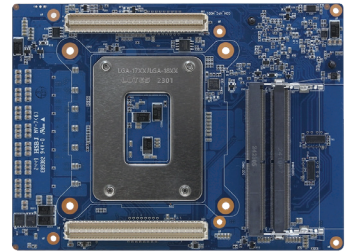
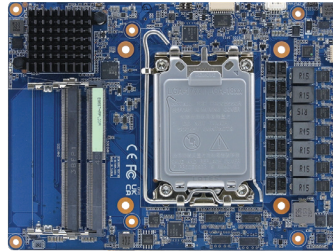
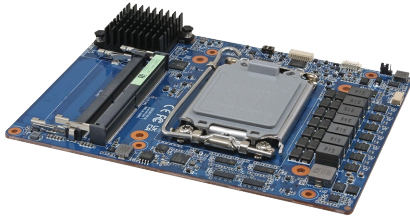
SPECIFICATIONS

System	
CPU	LGA17xx/LGA18xx socket supports 12/13/14th Gen Intel® Core™ i9/i7/i5/i3 Processor, up to 65W TDP
Platform Controller Hub	Intel® R680E chipsets
System Memory	4 x 262-Pin DDR5 SO-DIMM sockets support up to 128GB, 3600~4000MT/s, optional ECC support (CPU dependent)
BIOS	AMI uEFI BIOS, 256 Mbit SPI Flash ROM
I/O Chipset	EC ITE IT5782
Ethernet	2 x Intel® Ethernet Controller I226-V/I226-LM (2.5GbE)
Audio	HD Audio
Watchdog Timer	H/W Reset, 1Sec. ~ 65535Sec. and 1Sec./Step
H/W Status Monitor	Monitoring System Temperature Voltage and FAN Status with Auto Throttling Control
Expansion	1 x PCIe Gen5 x16 (can be bifurcated to 2 x PCIe Gen5 x8) 1 x PEG x4 2 x PCIe x4 9 x PCIe Gen3 x1 1 x PCIe Gen3 x1 for BMC (by the carrier board)
TPM	TPM 2.0 (Optional)
OS Support	Windows 11 LTSC Linux
Display	
Chipset	Intel® UHD Graphics 770 up to 32EUs
Resolution	3 x DDI ports support configurable DP 1.4a or HDMI 2.1b 1 x eDP 1.4b
Multi-Display	Supports 4 Independent Display

I/O	
USB	Supports 4 x USB 3.2 Gen2x2 Supports 8 x USB 2.0
SMBus	Supports 1 x SMBus
COM Port	Supports 2 x UART
GPIO	Supports 12 ports GPIO
SATA	Supports 2 ports SATA III
MIO	1 x Smart FAN on COM-HPC module Supports 1 x Smart FAN, Audio, I2C, GSPI, IPMB, SPI
Mechanical, Power, and Environment	
Operating Temperature	With CPU cooler: 0°C ~ 60°C (32°F ~ 140°F) with 0.5m/s air flow
Storage Temperature	-20°C ~ 75°C (-4°F ~ 167°F)
Operating Humidity	40°C @ 95% Relative Humidity, Non-condensing
Form Factor	COM-HPC Client size C
Dimensions	6.30" x 4.72" (160 x 120 mm)
Weight	TBD



SPECIFICATIONS / ADDITIONAL PRODUCT PHOTOS



BLOCK DIAGRAM

ORDERING INFORMATION

Model Name	CPU	Description
ESM-HRPL		Please contact BCMSales@bcmcom.com for details.

PACKING LIST

- ✓ 1 x ESM-HRPL COM-HPC module



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Tailored Hardware Solutions, Delivered with Excellence:
Your Go-To Partner for Industrial Computing Design



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